Power MOSFET 60 V, 13 mΩ, 58 A, Dual N–Channel Logic

Level, Dual SO–8FL

Features

- Small Footprint (5x6 mm) for Compact Designs
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVMFD5873NLWF Wettable Flanks Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- This is a Pb–Free Device

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parar	Parameter			Value	Unit
Drain-to-Source Voltage		V _{DSS}	60	V	
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain Current $R_{\Psi,J-mb}$ (Notes 1,		T _{mb} = 25°C	۱ _D	58	A
2, 3, 4)	Steady	$T_{mb} = 100^{\circ}C$		41	
Power Dissipation	State	$T_{mb} = 25^{\circ}C$	PD	107	W
R _{ΨJ-mb} (Notes 1, 2, 3)		$T_{mb} = 100^{\circ}C$		54	
Continuous Drain Cur-	Steady State	T _A = 25°C	Ι _D	10	А
rent R _{θJA} (Notes 1, 3 & 4)		$T_A = 100^{\circ}C$		7.0	
Power Dissipation		T _A = 25°C	PD	3.1	W
$R_{\theta JA}$ (Notes 1 & 3)		$T_A = 100^{\circ}C$		1.6	
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	190	A
Operating Junction and	Storage T	emperature	T _J , T _{stg}	-55 to 175	°C
Source Current (Body Diode)		۱ _S	58	А	
Single Pulse Drain-to-Source Avalanche Energy ($T_J = 25^{\circ}C$, $V_{GS} = 10$ V, $I_{L(pk)} = 28.3$ A, L = 0.1 mH, $R_G = 25 \Omega$)		E _{AS}	40	mJ	
Lead Temperature for S (1/8" from case for 10 s)	ad Temperature for Soldering Purposes 8" from case for 10 s)		ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Mounting Board (top) – Steady State (Notes 2, 3)	$R_{\Psi J-mb}$	1.4	°C/W
Junction-to-Ambient - Steady State (Note 3)	Reia	48	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Psi (Ψ) is used as required per JESD51–12 for packages in which substantially less than 100% of the heat flows to single case surface.

3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

4. Maximum current for pulses as long as 1 second are higher but are dependent on pulse duration and duty cycle.

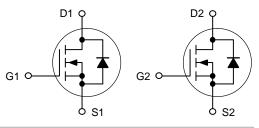


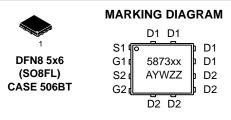
ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
60 V	13 mΩ @ 10 V	58 A
60 V	16.5 mΩ @ 4.5 V	30 A

Dual N–Channel





5873N	L = Specific Device Code
	for NVMFD5873NL
5873L\	N = Specific Device Code
	for NVMFD5873NLWF
А	= Assembly Location
Y	= Year
W	= Work Week
ZZ	= Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping [†]		
NVMFD5873NLT1G	DFN8 (Pb–Free)	1500 / Tape & Reel		
NVMFD5873NLWFT1G	DFN8 (Pb-Free)	1500 / Tape & Reel		

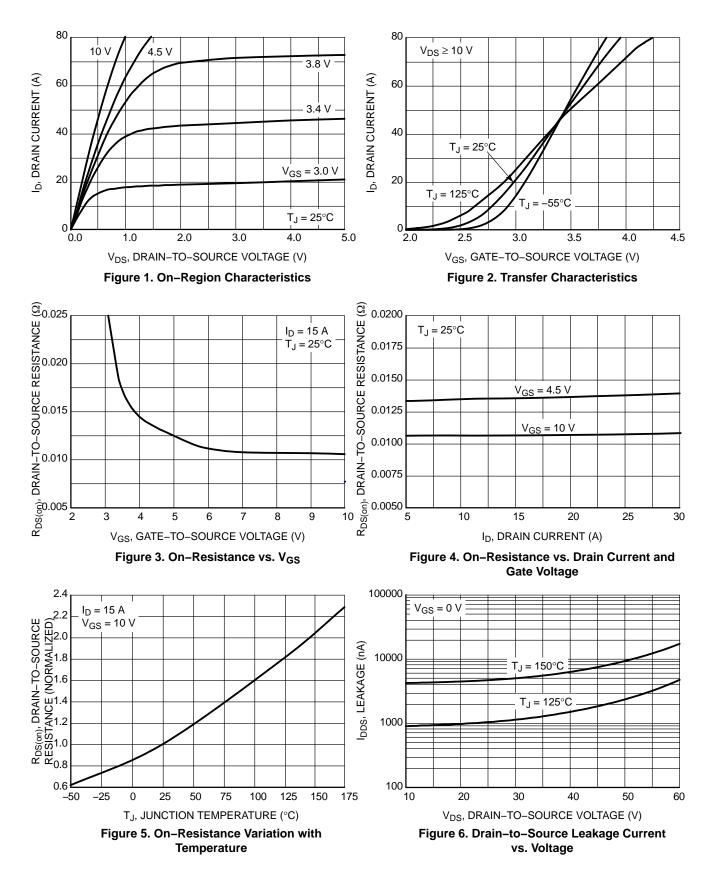
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

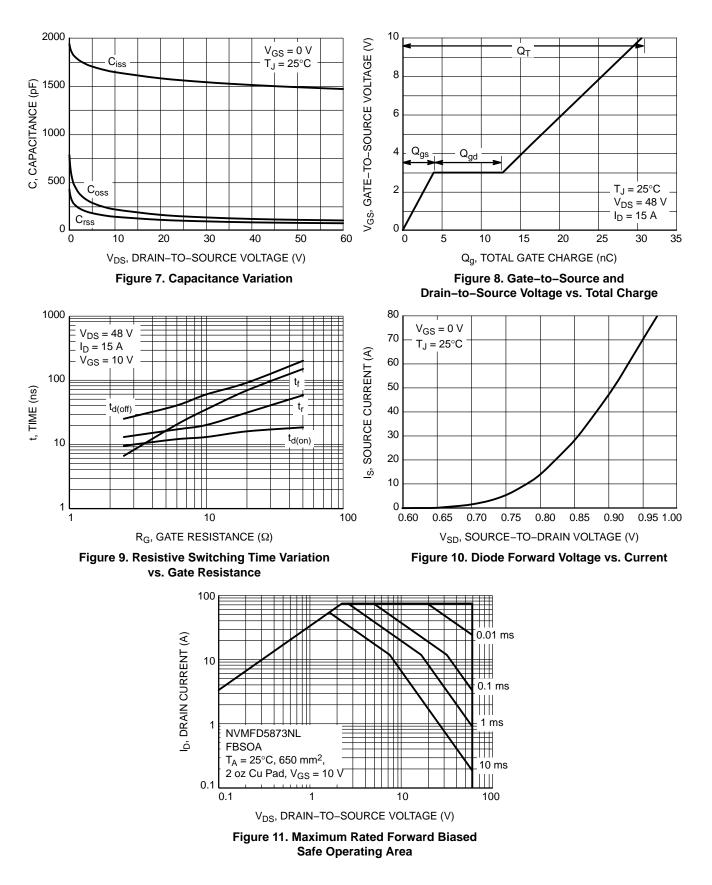
Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit
OFF CHARACTERISTICS						•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				54.9		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{CS} = 0 V_{c}$	$T_J = 25^{\circ}C$			1.0	μΑ
		V _{GS} = 0 V, V _{DS} = 60 V	$T_J = 125^{\circ}C$			100	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±20 V			±100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	250 μΑ	1.5		2.5	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.8		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D	= 15 A		10.7	13	mΩ
		V _{GS} = 4.5 V, I _D	= 10 A		13.6	16.5	
Forward Transconductance	9 FS	V _{DS} = 5.0 V, I _D = 15 A			15		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{iss}			1560		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, f = 1.0 MH		145		-	
Reverse Transfer Capacitance	C _{rss}			98			
Total Gate Charge	Q _{G(TOT)}				16.5		nC
Threshold Gate Charge	Q _{G(TH)}	Vcs = 4.5 V. Vps	s = 48 V.		1.3		1
Gate-to-Source Charge	Q _{GS}	V _{GS} = 4.5 V, V _{DS} I _D = 15 A		4.0		1	
Gate-to-Drain Charge	Q _{GD}				8.8		1
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48V, I _D = 15 A			30.5		nC
SWITCHING CHARACTERISTICS (N	ote 6)						
Turn-On Delay Time	t _{d(on)}				10.8		ns
Rise Time	tr	Vcs = 4.5 V. Vcs	e = 48 V.		51		1
Turn-Off Delay Time	t _{d(off)}	V_{GS} = 4.5 V, V_{DS} = 48 V, I_{D} = 15 A, R_{G} = 2.5 Ω			21		
Fall Time	t _f		·		42.6		
Turn-On Delay Time	t _{d(on)}				9.5		ns
Rise Time	t _r	Vcs = 10 V. Vps	= 48 V.		13		
Turn–Off Delay Time	t _{d(off)}	$V_{GS} = 10 \text{ V}, V_{DS} = 48 \text{ V}, \\ I_D = 15 \text{ A}, \text{ R}_G = 2.5 \Omega$			25		
Fall Time	t _f				6.6		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS				•	•	
Forward Diode Voltage	V _{SD}	V_{SD} $V_{GS} = 0 V,$ $I_S = 15 A$	$T_J = 25^{\circ}C$		0.8	1.0	V
			T _J = 125°C		0.7		1
Reverse Recovery Time	t _{RR}				22.4		ns
Charge Time	t _a	V_{GS} = 0 V, d_{IS}/d_t = 100 A/µs, I _S = 15 A			14.5		1
Discharge Time	t _b				9.0	1	1
Reverse Recovery Charge	Q _{RR}				18		nC

5. Pulse Test: pulse width = 300 μ s, duty cycle \leq 2%. 6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

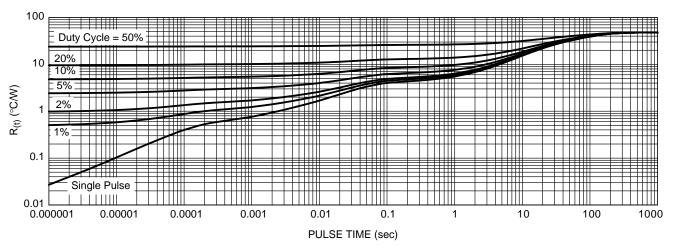
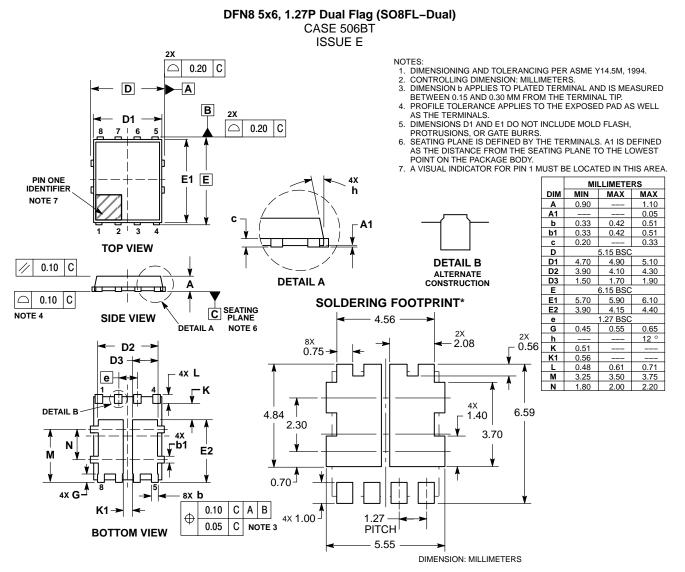


Figure 12. Thermal Response

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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